

Denial of Service during Bluetooth LE authentication and connection



1 Summary

An issue identified in the Texas Instruments Bluetooth® stack causes a Denial of Service (DoS) condition. The potential vulnerability can be exploited by sending a crafted LL_Pause_Enc_Req packet during the Bluetooth LE connection establishment phase. When processed by an affected device, this malformed packet can cause the device to enter an unresponsive state, requiring a manual reset to restore normal operation.

2 Vulnerability

TI PSIRT ID

TI-PSIRT-2025-070274

CVE ID

CVE-2025-44528

CVSS Score

The CVSS base score is 6.5.

Note

The CVSS scoring for this advisory considers the vulnerability as an adjacent attack vector, differing from the network attack vector listed in the CVEID

CVSS Vector

[CVSS:3.1/AV:A/AC:L/PR:N/UI:N/S:U/C:N/I:N/A:H](#)

Affected Products

Part	Software Name	Software Version	BLE Stack Name	BLE Stack Version
CC2651P3, CC2651R3, CC2651R3SIPA, CC2642R, CC2652R, CC2652P, CC1352R, CC1352P, CC2652RSIP, CC2652PSIP, CC2642R-Q1, CC2652R7, CC2652P7, CC1352R7, CC1352P7	SIMPLELINK-CC13XX-CC26XX-SDK: SIMPLELINK-LOWPOWER-F2-SDK	SimpleLink™ CC13XX CC26XX SDK 7.41.00.17	BLE5-Stack	v2.2.8
CC2340R5, CC2340R5-Q1, CC2340R2	SIMPLELINK-LOWPOWER-F3-SDK	SimpleLink Low Power F3 SDK 9.10.00.00	BLE5-stack	v3.3.4
CC2745R10-Q1, CC2745R7-Q1, CC2744R7-Q1, CC2745P10-Q1, CC2755R10, CC2755P10	SIMPLELINK-LOWPOWER-F3-SDK	SimpleLink Low Power F3 SDK 9.10.00.00	BLE5-stack	v3.3.4
CC2640R2F, CC2640R2L, CC2640R2F-Q1	SIMPLELINK-CC2640R2-SDK: SimpleLink CC2640R2 SDK - Bluetooth low energy	SIMPLELINK-CC2640R2-SDK 5.30.01.11	BLE-Stack	v3.03.08.00 and earlier
			BLE5-Stack	v1.01.14.00 and earlier
CC1350	SIMPLELINK-CC13X0-SDK: SimpleLink Sub-1GHz CC13x0 Software Development Kit	SIMPLELINK-CC13X0-SDK 4.20.02.07	BLE-Stack	v2.03.11.00 and earlier
CC2640, CC2650, CC2650MODA	N/A	2.02.08.12	BLE-STACK-2-X	v2.02.07.06 and earlier
CC2540, CC2541	N/A	1.05.02.00	BLE-STACK-1-X	v1.05.02.00 and earlier

Potentially Impacted Features

The potential vulnerability can impact TI Bluetooth Low Energy devices running the affected SDK versions with link layer encryption enabled and performing encryption operations during connection establishment, if implemented.

Suggested Mitigations

The following SDK releases addresses the potential vulnerability:

Affected SDK	First SDK Version with Mitigations	First BLE Stack Version with Mitigations
CC13XX-26XX-SDK, BLE5-STACK	SimpleLink Low Power F2 SDK 9.20.00.00	v3.4.0 (upcoming release)
CC2340 SDK, BLE5-STACK	SimpleLink Low Power F3 SDK 9.11.01.00	v3.3.4
CC27xx SDK, BLE5-STACK	SimpleLink Low Power F3 SDK 9.11.01.00	v3.3.4
CC2640R2 SDK, BLE5-STACK	In upcoming release	In upcoming release
CC2640R2 SDK, BLE-STACK	In upcoming release	In upcoming release
CC1350, CC26x0, CC25x0 SDK, BLE-STACK	N/A ⁽¹⁾	N/A ⁽¹⁾

- (1) Mitigation on these device stacks is not supported as this is a fix to the BLE stack in devices' ROM, and with limited ROM patch space on these devices, the patch memory is being reserved for more critical PSIRT tickets in the future. If you have questions, please reach out to psirt@ti.com.

The software containing the mitigation described in this document can be distributed to already deployed devices through all enabled software update mechanisms, including Over-the-Air Download (OTA/OAD) update procedures.

References

- *Core Specification 5.3*. (2021, July 13). Bluetooth. Retrieved April 28, 2026 from <https://www.bluetooth.com/specifications/specs/core-specification-5-3/>
- Texas Instruments (2026). *Vulnerability Report: Premature Encryption Pause Attack on LP-CC2652RB* [Source code]. GitHub. https://github.com/yangting111/BLE_TEST/blob/main/result/PoC/TI/Accept_Pause_Enc_Req.md

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